

AMENDMENTS TO THE CLAIMS

1. (Currently amended) A substrate for a device package comprising:
 - a lower portion of a package having a top surface, said top surface having a plurality of corners;
 - an intermediate metalization layer on ~~[[a]]~~ said top surface of said lower portion;
 - an upper portion of said package on said top surface of said lower portion, a portion of said lower portion and a corresponding portion of said intermediate metalization layer extending beyond said upper portion such that one of said corners is unique relative to other said corners ~~said corresponding portion of said intermediate metalization layer is visible beyond the extent of said upper portion when viewed from a direction normal to said top surface.~~
2. (Original) The substrate of Claim 1, said lower and upper portions comprising a ceramic.
3. (Original) The substrate of Claim 1, said lower portion comprising a layered ceramic portion containing electrical interconnections.
4. (Currently amended) The substrate of Claim 1, ~~said visible corner portion~~ comprising a plating on said extending portion of said lower ~~visible corner~~ portion.
5. (Currently amended) The substrate of Claim 1, comprising an electrical device electrically connected to portions of said intermediate metalization layer.
6. (Currently amended) The substrate of Claim 1, comprising an electrical device electrically connected to circuit portions of said intermediate metalization layer, said ~~visible corner~~ corresponding portion electrically isolated from said circuit portions of said intermediate metalization layer electrically connected to said device.
7. (Original) The substrate of Claim 1, comprising an electrical device and a lid enclosing said device between said lid and said substrate.
8. (Currently amended) The substrate of Claim 1, said upper portion having a void over said visible corner region of said intermediate metalization layer, said void allowing visibility to said intermediate metalization layer.
9. (Original) The substrate of Claim 8, said void used to mechanically position said substrate.

10-19. (Canceled)

20. (New) A substrate for a device package comprising:

a first portion of a package having a first surface, said first surface having a plurality of corners;

an intermediate metalization layer on said first surface of said first portion;

a second portion of said package supported by said first surface of said first portion, a first surface portion of said first portion and a corresponding portion of said intermediate metalization layer extending beyond said second portion such that one of said corners is unique relative to other said corners.

21. (New) The substrate of Claim 20, said first portion comprising a ceramic portion containing electrical interconnections.

22. (New) The substrate of Claim 20, said first portion comprising electrical connections on a second surface opposite said first surface.

23. (New) The substrate of Claim 20, comprising an electrical device electrically connected to circuit portions of said intermediate metalization layer, said corresponding portion of said said intermediate metalization layer electrically isolated from said circuit portions of said intermediate metalization layer.

24. (New) The substrate of Claim 1, said second portion having a void over said corresponding portion of said metalization layer.

25. (New) The substrate of Claim 1, said first surface of said first portion having four corners, wherein only one of said corners extends beyond said second portion.

26. (New) The substrate of Claim 20, said first portion comprising a ceramic portion.

27. (New) The substrate of Claim 20, said first portion comprising a polyamide.

28. (New) The substrate of Claim 20, said first portion comprising a plastic.